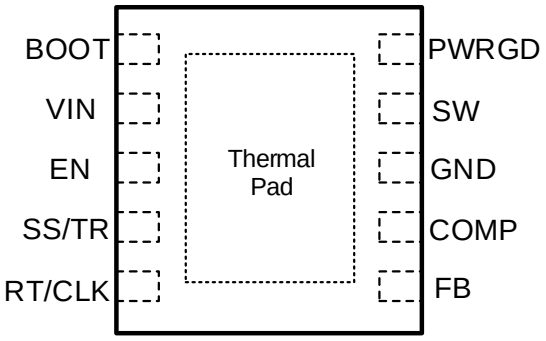
REVISION HISTORY

DEVICE ORDER INFORMATION

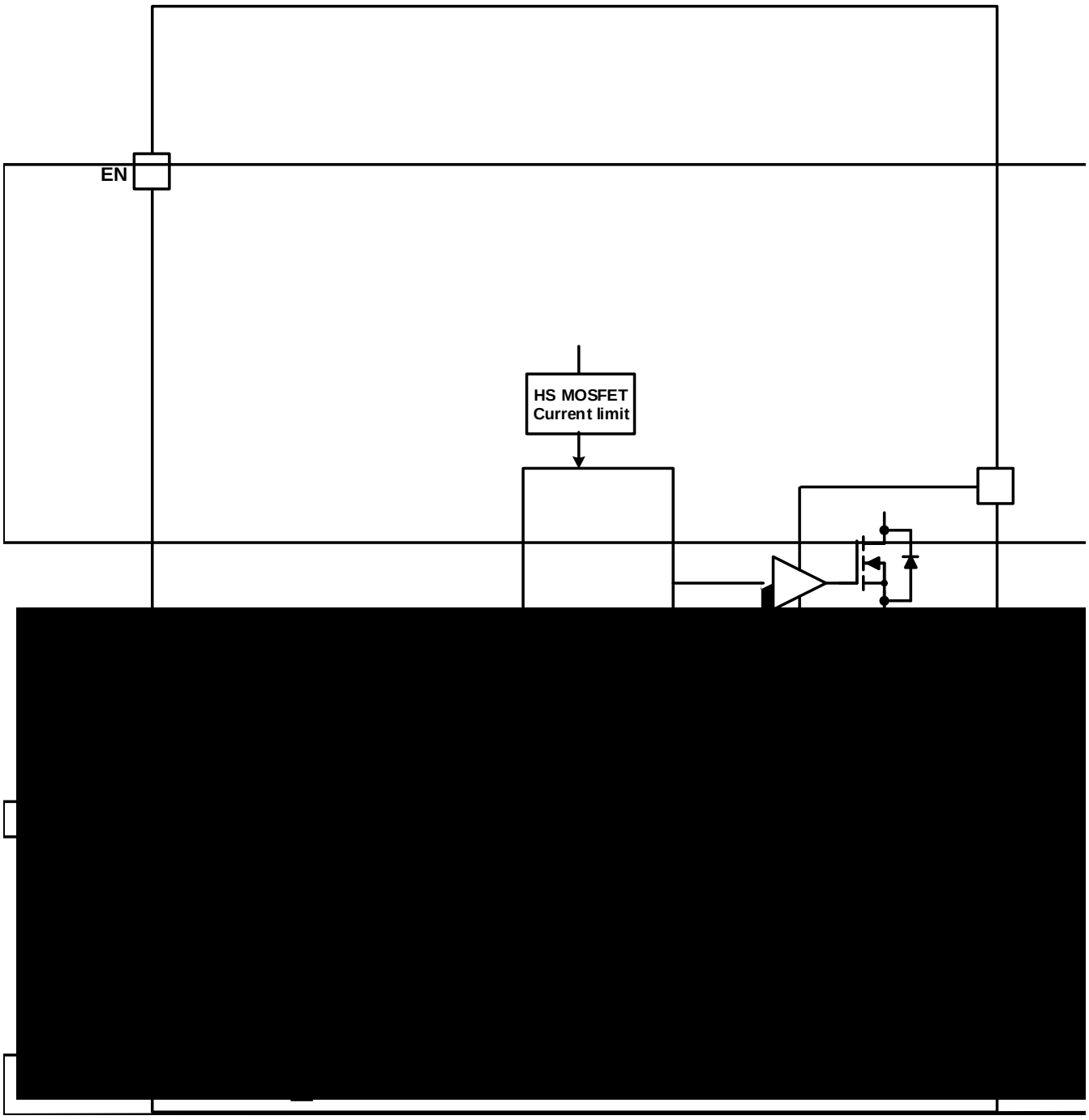
ABSOLUTE MAXIMUM RATINGS

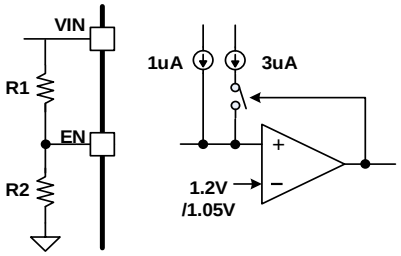
PIN CONFIGURATION

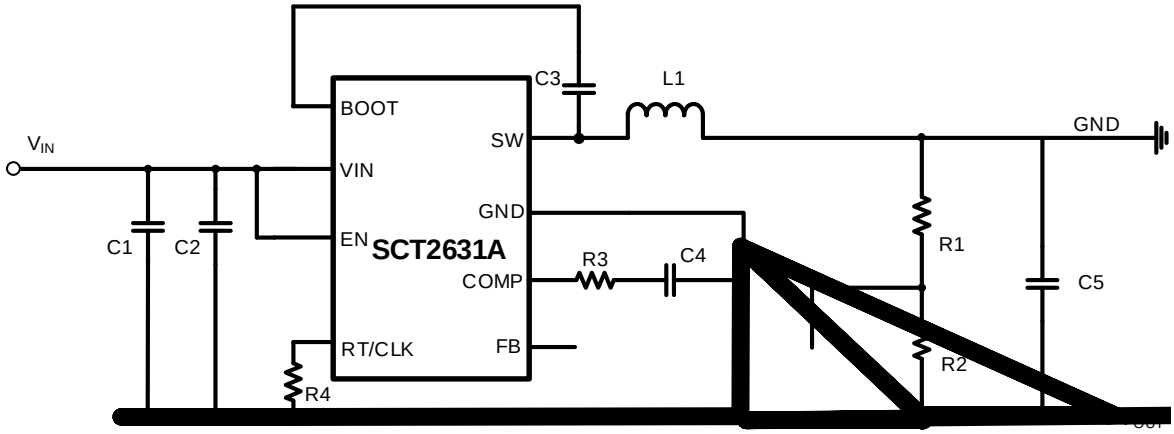


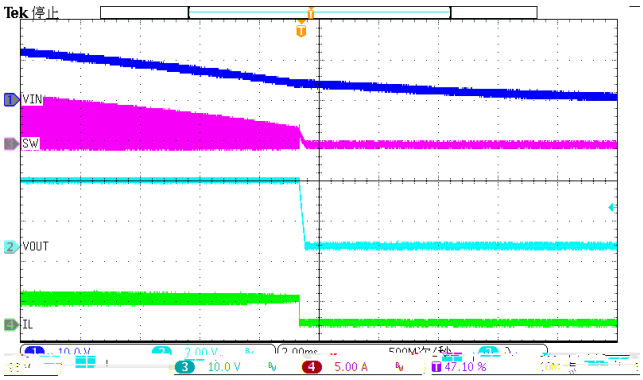
RECOMMENDED OPERATING CONDITIONS

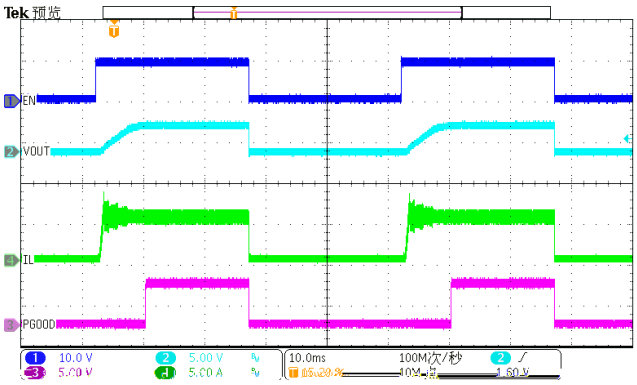
FUNCTIONAL BLOCK DIAGRAM

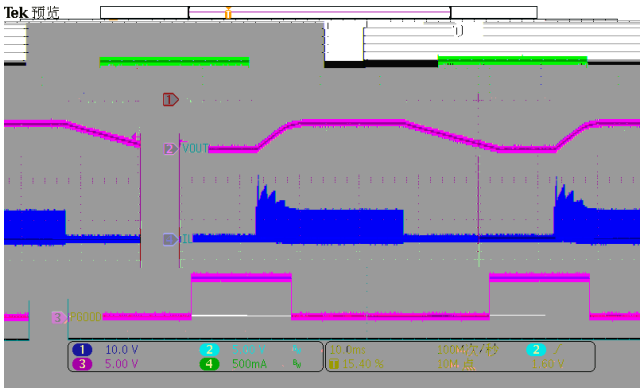


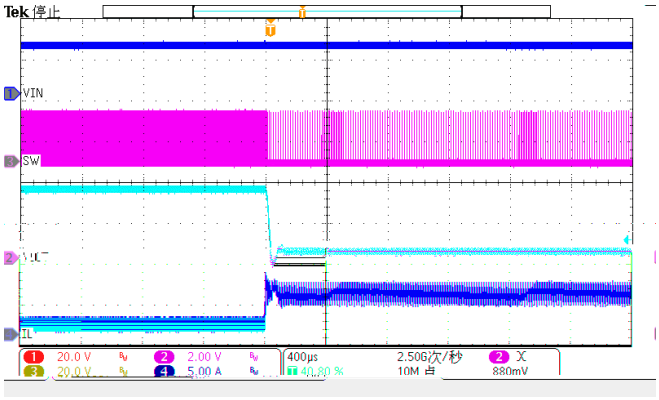

VIN
R1
EN
R2
1uA
3uA
1.2V
/1.05V

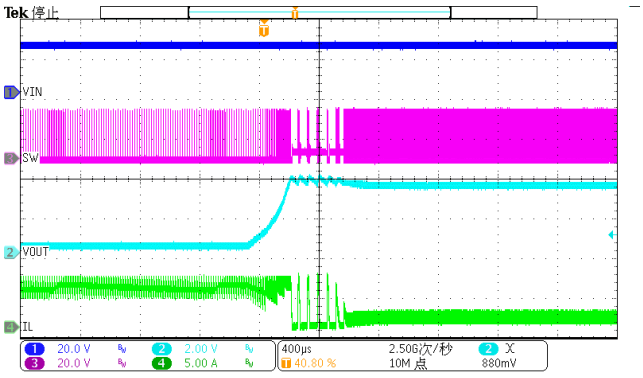

C3
L1
BOOT
SW
GND
VIN
GND
EN
SCT2631A
COMP
RT/CLK
FB
C1
C2
R3
C4
R1
C5
R2
R4

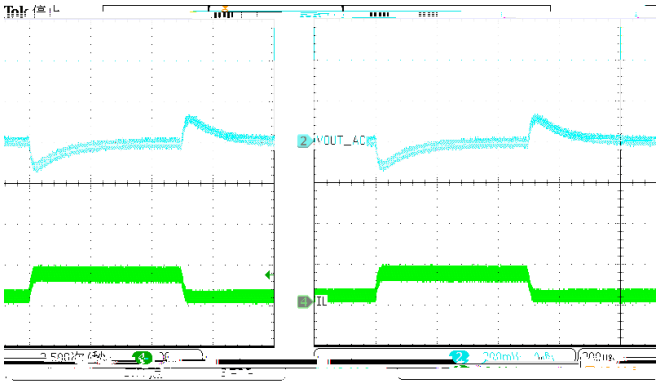

Tek 停止
VIN
SW
VOUT
IL
10.0 V
5.00 A
47.10 %

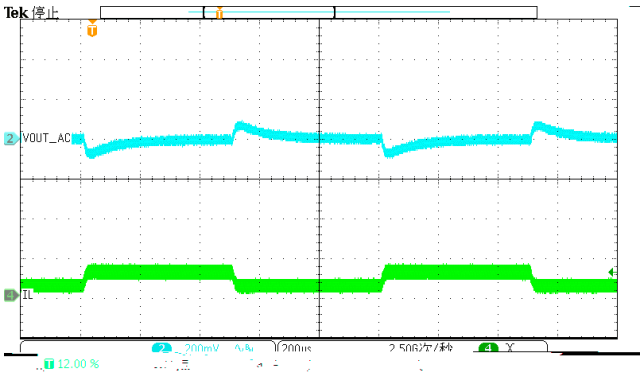

Tek 预览
EN
VOUT
IL
PGOOD
10.0 V
5.00 V
5.00 A
10.0ms
100M次/秒

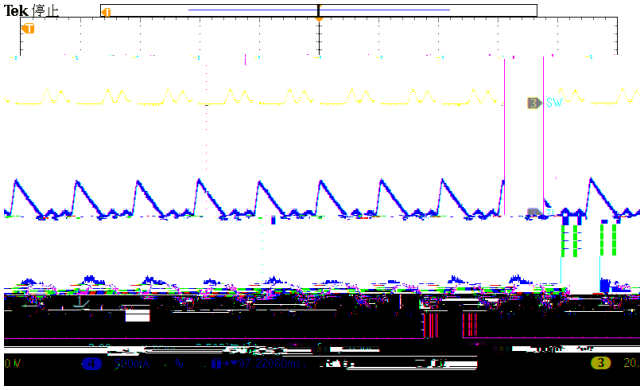

Tek 预览
VOUT
IL
PGOOD
10.0 V
5.00 V
500mA

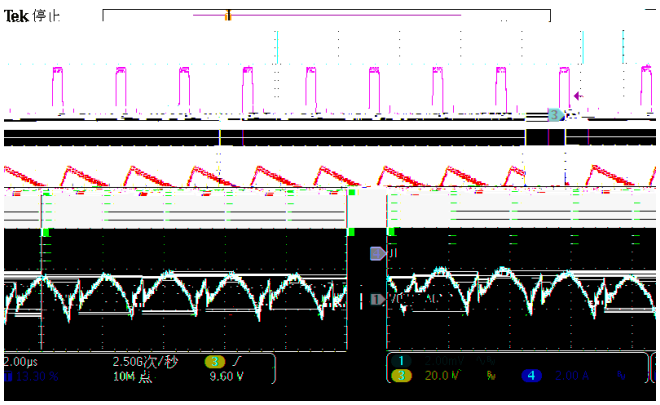

Tek 停止
VIN
SW
VOUT
IL
20.0 V
2.00 V
5.00 A
400µs
2.50G次/秒
10M 点
880mV

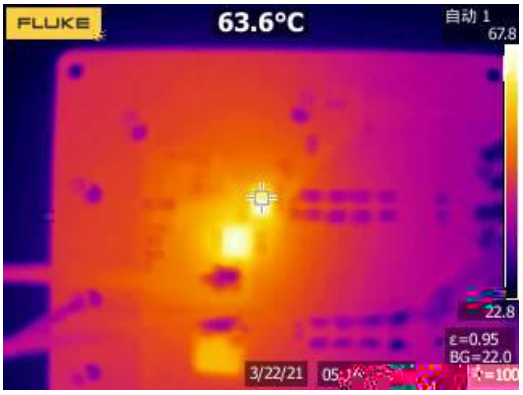

Tek 停止
VIN
SW
VOUT
IL
20.0 V
2.00 V
5.00 A
400µs
40.80 %
2.50G次/秒
10M 点
880mV


Tek 停止
VOUT_AC
IL

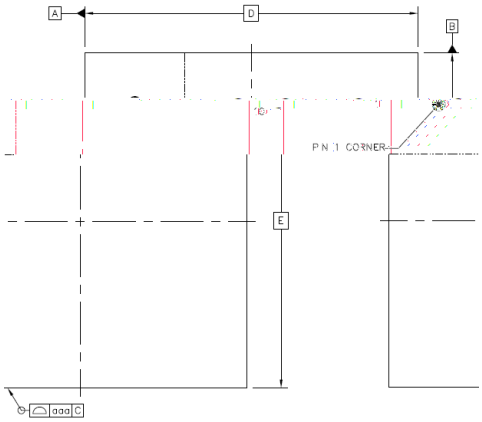

Tek 停止
VOUT_AC
IL

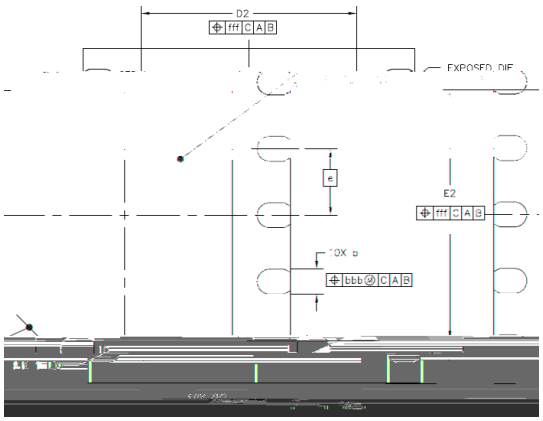

Tek 停止
SW

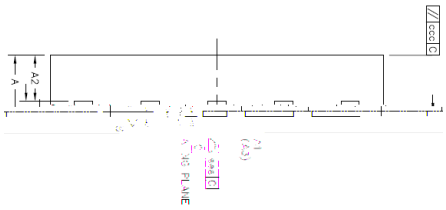

Tek 停止
2.00µs
2.50GS/s
10M 点
9.60 V
20.0 V
2.00 A

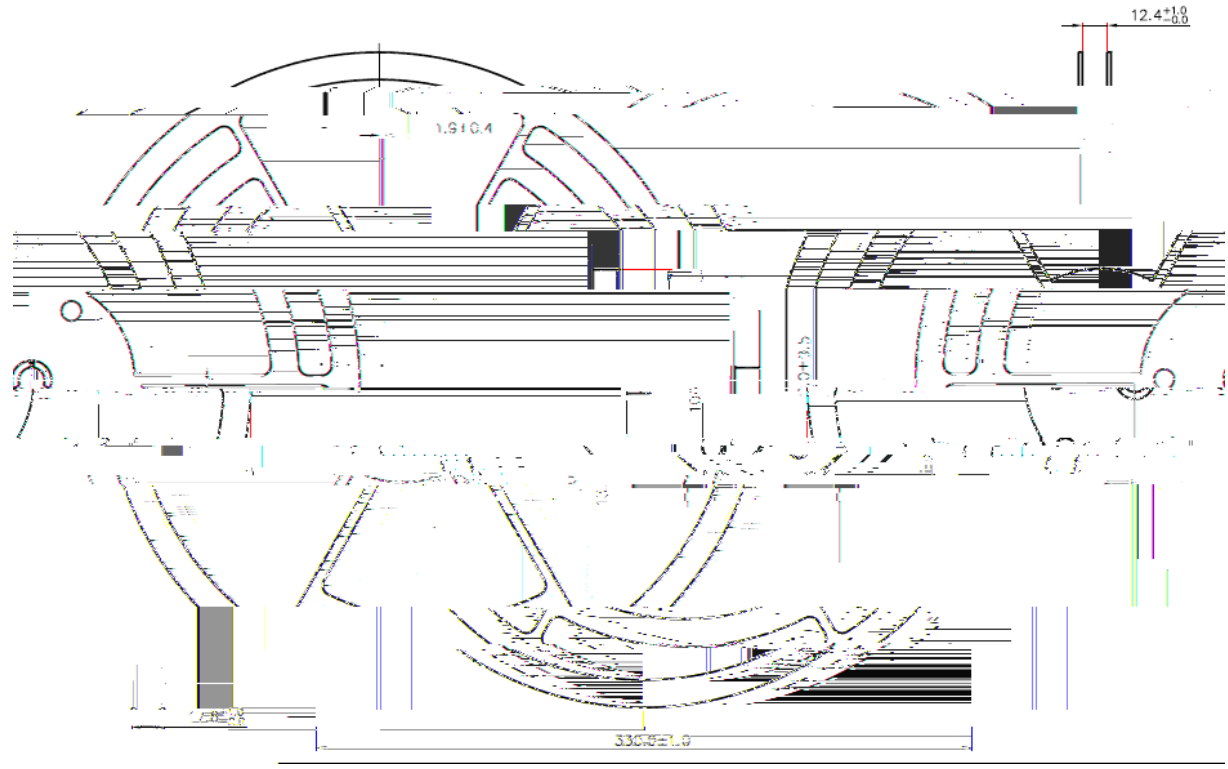
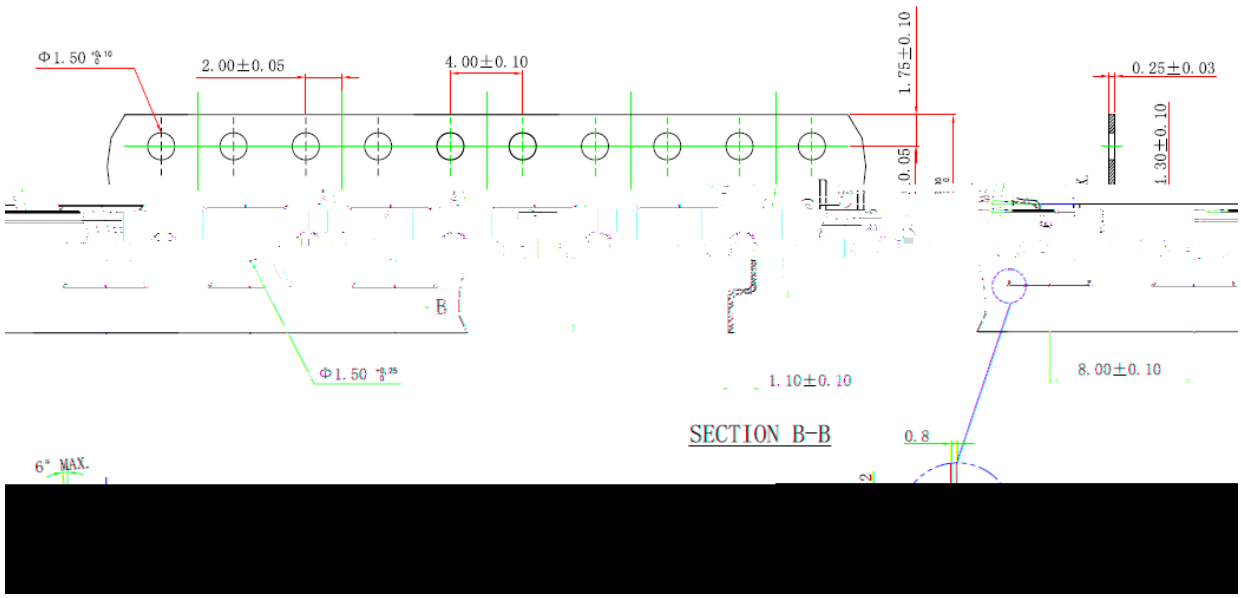

FLUKE
63.6°C
自动 1
67.8
22.8
ε=0.95
BG=22.0
3/22/21

PACKAGE INFORMATION







1. Drawing proposed be made a JEDEC package utine MO - 220 variation.
2. Drawing not to scale.
3. All linear dimensions re in millimeters.
4. Thermal pad hall be soldered gn the board.
5. Dimensions f exposed pad gn bottom f package o ot include mold flash.
6. Contact PCB board fabrication for minimum solder mask web Sglerances between the pins.

TAPE AND REEL INFORMATION